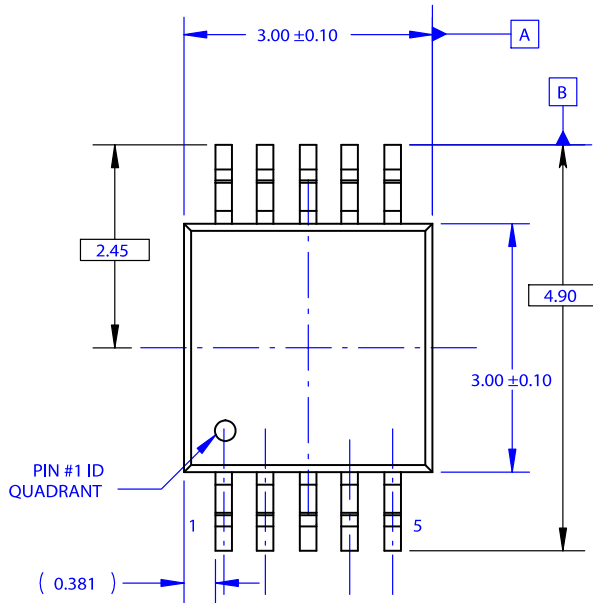
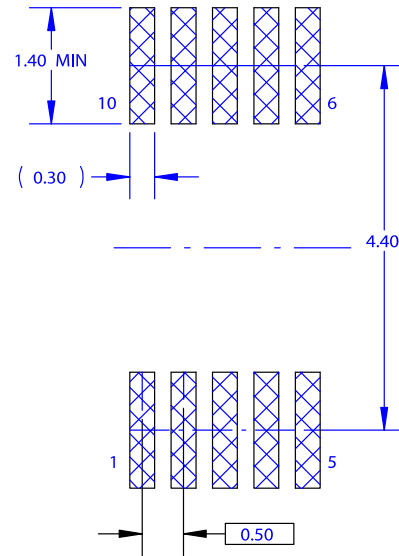


**MSOP10**  
**CASE 846AP**  
**ISSUE O**

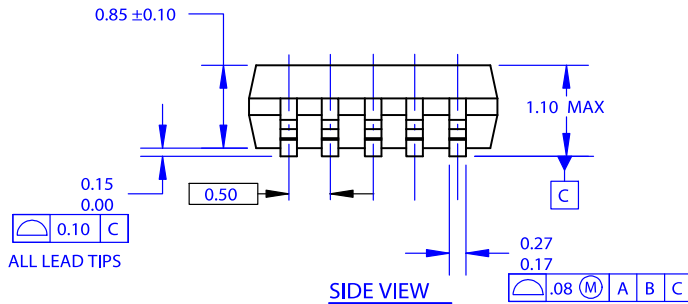
DATE 31 JAN 2017



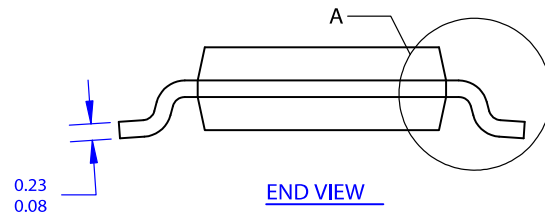
TOP VIEW



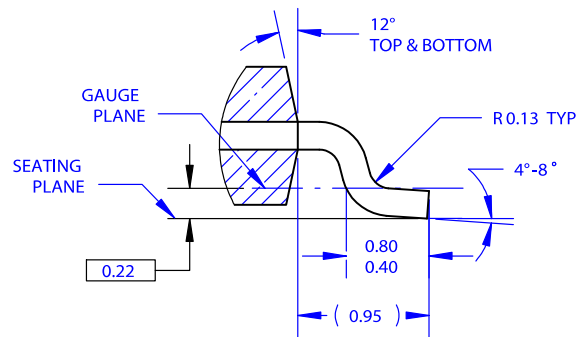
LAND PATTERN RECOMMENDATION



SIDE VIEW



END VIEW



DETAIL A  
SCALE 20 : 1

**NOTES: UNLESS OTHERWISE SPECIFIED**

- A. THIS PACKAGE CONFORMS TO JEDEC MO-187 VARIATION BA.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES AS PER ASME Y14.5-1994.
- E. LAND PATTERN AS PER IPC7351#SOP50P490X110-10AN

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<b>DESCRIPTION:</b>	<b>MSOP10</b>	<b>PAGE 1 OF 1</b>

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